Thermionic Field Emission Transport in Carbon Nanotube Transistors

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Abstract

With experimental and analytical analysis, we demonstrate a relationship between the metal contact work function and the electrical transport properties saturation current (I_{sat}) and differential conductance (\sigma_{sd}) in ambient exposed carbon nanotubes (CNT). A single chemical vapor deposition (CVD) grown 6 mm long semiconducting single-walled CNT is electrically contacted with a statistically significant number of Hf, Cr, Ti, Pd, and Au electrodes, respectively. The observed exponentially increasing relationship of I_{sat} and \sigma_{sd} with metal contact work function is explained by a theoretical model derived from thermionic field emission. Statistical analysis and spread of the data suggest that the conduction variability in same CNT devices results from differences in local surface potential of the metal contact. Based on the theoretical model and methodology, an improved CNT-based gas sensing device layout is suggested. A method to experimentally determine gas-induced work function changes in metals is also examined.

Keywords: carbon nanotube • thermionic field emission • schottky barrier • electrical transport • saturation current • differential conductance

Results

CNTFETs are fabricated using e-beam lithography and physical evaporation onto centimeter long, aligned, laminar flow grown thermal chemical vapor deposition (CVD) CNTs. Metal contacts were placed in a linear fashion along the tube length with an equidistance of 1 µm gap (Figure 1a). After fabrication, additional CNTs on the sample were removed with 100—150 W O₂ plasma, while areas containing FETs were covered with protective sacrificial layer of photo resist. This resist was removed, and the sample was cleaned twice by UV exposure and further rinsed in acetone to remove any residue. Atomic force microscopy (AFM) measurements confirmed the cleanliness of the sample. We focus on two samples in this report, the first contains 120 electrodes (114 devices) on a single 6 mm long semiconducting CNT of 1.7 nm diameter with 86 devices electrically active at the first measurement (75.4% yield). The diameter was confirmed by AFM, and the lack of 100% yield results from regions where the single CNT was damaged during fabrication. Sample 1 utilizes the metals Ti, Pd, Cr, and Hf as metal contacts. In addition, to confirm the model consistency, we prepared a second sample incorporating only Ti and Au electrodes on a 5 mm long, 1.53 nm diameter semiconducting CNT. Optical images of samples are shown in Figure 1a and a magnified AFM image in Figure 1b. The metals Au, Ti, Pd, Cr, and Hf were chosen because they are nonferromagnetic and possess a wide range of work functions (4.0—5.2 eV).

Characterization and Discussion

I–V measurements were performed on the two samples in ambient environment and...
using a probe station. A back gate bias of $V_g = -15$ V was found to be sufficient to bias all devices in the hole-conducting on-state. This restriction was necessary to prevent the existence of multiple carrier types and eliminate the effect of threshold voltage shifts in the analysis of different metals. Figure 1c shows the clear $I_{sd}$ relationship with metals, with an order of $I_{sd}(\text{Hf}) < I_{sd}(\text{Cr}) < I_{sd}(\text{Ti}) < I_{sd}(\text{Pd})$. $I_{sat}$ is found by extrapolating the linear region of $\ln(I_{sd})$ vs $V_{sd}$ to $V_{sd} = 0$ V, as illustrated in Figure 1c. The corresponding $\sigma_{sd}$ curves are also provided in Figure 1d. To calculate $\sigma_{sd}$, $I_{sd}(V_{sd})$ curves were smoothed with a 16 point Savitzky Golay filter, and the resulting curves are differentiated. The data were tabulated by metal type, and differential conductance at $V_{sd} = 0$ point was chosen from each device for comparison.

To accurately compare $\sigma_{sd}$ and $I_{sat}$ for different metal contacts, statistical analysis is performed on the raw data to check the normality of each distribution. For data with a normal distribution, the mean will be used as an accurate comparative value to test for a dependence between metal $\sigma_{sd}$ and $I_{sat}$. Figure 2a shows a histogram of differential conductance by metal type. Although there is an overlap in the differential conductance for each metal, a distinct trend for $\sigma_{sd}$ is observed with an order, $\sigma_{sd}(\text{HF}) < \sigma_{sd}(\text{Cr}) < \sigma_{sd}(\text{Ti}) < \sigma_{sd}(\text{Pd})$. It will be demonstrated later in this report that the overlap is attributable to the widely varying and often overlapping work functions for each of the metal species. A Shapiro–Wilk normal distribution test of the data with $\alpha = 0.05$ permitted rejection of the normal distribution hypothesis for the metal Pd due to the wide asymmetric distribution of the data. In this case, $\sigma_{sd}$ for Pd-contacted devices is very unlikely to be representative of a normal distribution, as expected due to the ohmic qualities of many devices limiting the upper range of conductance. To examine the dependence of mean $\sigma_{sd}$ on work function of Hf, Cr, Ti, and Au metal, $\ln(\sigma_{sd})$ vs work function (see Table S1, Supporting Information, for more details) is plotted in Figure 2b. A linear relationship between $\ln(\sigma_{sd})$ and work function is observed, although nonlinearity comes into play at large work function.

In order to understand the relationship between $\ln(\sigma_{sd})$ and work function, we begin with TFE current, since strict thermionic emission current and field emission current will give rise to a linear relationship. Pure thermionic emission theory also predicts that $\ln(\sigma_{sd}) = \Phi_{metal}/(kT) = 38.61$ (see data S1, Supporting Information). A simple linear fit of the data produces a slope <10, indicating the presence of a large field emission component. Therefore, a mixed TFE theory adapted from Crowell et al. and Padovani et al. is incorporated to fit the experimental observations. TFE current at a metal–semiconductor junction is described by

$$
I_{sd} = I_{sat} \left[ \frac{e^{\frac{E_{00} - V_{sd} + \zeta_2}{kT}} - 1}{\text{erf} \left( \frac{E_{00} - V_{sd} + \zeta_2}{kT} \right)} \right]^{1/2}
$$

with

$$
I_{sat} = \frac{A \pi^{1/2} E_{00}^{1/2} (\Phi_b - V_{sd} + \zeta_2)^{1/2} e^{\frac{\Phi_b - V_{sd} + \zeta_2}{kT}}}{kT \cosh \left( \frac{E_{00}}{kT} \right)}
$$

where $A$ is the Richardson constant, $T$ is temperature in Kelvin, $k$ is the Boltzmann constant, $\Phi_b$ is the Schottky barrier height, $\zeta_2 = E_F - E_v$, $E_F$ is the CNT Fermi level, $E_v$ is the CNT valence band, $E_{00}$ is a TFE tunneling parameter, and $E_0 = E_{00} \coth(E_{00}/kT)$. Applying $V_g = -15$ V
results in $\zeta_2 = E_b - E_g \approx 0$, simplifying the system. We utilize the Schottky–Mott relationship and assume that $\Phi_b \approx \Phi_s - \Phi_{m}$. From the value of graphite, electron affinity, $X_{CNT} \approx 4.5$, and for a CNT diameter of 1.7 nm, energy gap, $E_g \approx 0.65$ eV. Therefore, $\Phi_b \approx 5.15 - \Phi_{m}$, allowing replacement of the barrier dependence with a work function dependence. Further differentiating eq 1 and substituting eq 2 with the above relationships for $\Phi_{b}$, we derive (refer to data S2, Supporting Information for full derivation):

$$\ln(\sigma_{sd}) \approx \frac{1}{E_0} \ln(5.15 - \Phi_{m}) - \left(\frac{1}{E_0}\right)(5.15 - \Phi_{m}) \quad (3)$$

The fitting of this function to Hf, Cr, Ti, and Au is shown in Figure 2b. These results allow extraction of tunneling parameters $E_0 = 0.147$ eV = $E_{00}$ and $kT/E_{00} \approx 0.176$. The analysis of Crowell and Rideout is next used to fit $I_{sat}$ using equivalent work function and Fermi level assumptions (see data S3, Supporting Information). Pd was not included in the fitting, again because the sample mean was not reflective of the asymmetric distribution. Figure 3b shows $\ln(I_{sat})$ vs work function. The extracted tunneling parameters, $E_0 = 0.139 = E_{00}$ and $kT/E_{00} \approx 0.186$, are similar to those of differential conductance. This indicates that TFE and the derived model explain hole conduction in CNTFETs accurately.

Next, we consider the small variation of differential conductance (and $I_{sat}$) observed particularly in the case of Au and Cr in Figure 2. These metals are in contrast with Pd and Hf which in which a large variation was observed. Further, if one fits the raw data variance onto the observed curve of $\ln(\sigma_{sd})$ vs $\Phi_{m}$, the resulting work function spread falls within the expected work function range observed in ambient, indicating strong correlation between local work function and $\sigma_{sd}$. This phenomenon is demonstrated in Figure S1, Supporting Information. It is therefore concluded that variation of $\sigma_{sd}$ (and $I_{sat}$) is strongly related to environmental stability of metal, since the work function can be easily modified by adsorbates (particularly in the case of Pd and Hf). Implication of our measurements and theoretical model fitting is very intriguing, particularly for gas sensing. Physisorption of gases on a metal alters the work function and surface dipole according to exposure dose, often by well-known relationships. While the metals display no change of conductance with exposure, when used as a contact to a CNT, the work
function and dipole change will result in a measurable Isat and $\sigma_{sd}$ difference explainable by the relationships derived in this report.

An initial constraint to this sensing approach is the variation in conducting properties for different CNT under varying initial environmental conditions. However, the use of different diameter CNT will only affect CNT work function, and a simulation of curves increased (decreased) saturation current for smaller (larger) diameter CNT is seen in Figure 4. Similar trends are visible for each diameter, but the model fails at a lower metal contact work function due to the smaller CNT work function in larger diameter tubes. In CNT with a diameter 3.0 nm, Isat approaches 15 $\mu$A, similar to what has been observed experimentally. This suggests that with large work function metal contacts, the model can also predict Isat in other CNT devices. Therefore, simple I–V measurement during exposure will allow extraction of the work function of the metal, which will in turn allow one to measure the existence and even the concentration of certain gas species, which previously has been impossible to quantify.

CONCLUSION

In conclusion, we have demonstrated clear work function-dependent relationships for hole current $\sigma_{sd}$ and Isat. These parameters have been correlated by an existing contact-dominant conduction mechanism. Using TFE theory, tunneling parameters were extracted using a novel characterization method that strongly suggests an unpinned Fermi level in carbon nanotubes. Additionally, the results for $\sigma_{sd}$ and Isat fittings are in agreement, and the mathematical model presented can also be utilized to selectivity sense adsorbates in single CNT sensors via contact work function change. The process could further be reversed to detect work function of a metal in the case of a well-controlled environment, an important discovery for materials where local probing or optical methods are impossible.

METHODS

Fabrication. CNTs were synthesized by thermal CVD with FeCl₃ (Sigma Aldrich) in ethanol as a catalyst using flow rates of 16 sccm H₂, 8 sccm CH₄, and 100 sccm Ar in a 50 mm quartz tube. To contact the CNT with multiple metal species, modular Ti/Au probe-able pads were first fabricated with lead lines within ~15 $\mu$m of the CNT, via e-beam lithography (Raith eLine) and e-beam evaporation. Sequentially, Pd, Cr, Hf, and Ti electrodes were patterned with e-beam lithography, metal deposition performed by e-beam evaporation, and lift-off carried out in warm acetone. Post fabrication, CNTFET regions were covered with protective photoresist, and the samples were cleaned in 150 W O₂ plasma to remove unused CNTs.

Characterization. I–V curves were measured using a Keithley 236 (Source/Drain) and Keithley 237 (Gate/Drain) with Labview interface. Data analysis was performed using plotting software Origin 8.0 (Origin Laboratories).

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Supporting Information Available: Derivation of limiting thermionic conditions and of eq 3 for \( \sigma_{sd} \) and \( I_{sd} \), correlation of data spread for \( \sigma_{sd} \) and work function, and literature work functions. This information is available free of charge via the Internet at http://pubs.acs.org.

REFERENCES AND NOTES


